

**AMENDMENT****IN THE SPECIFICATION:**

Please replace the paragraph beginning on page 13, line 19 with the following replacement paragraph:

In one embodiment, first split output 232 from the BSC 114 may be indirectly monitored within the housing 120 of the photonic package 100. An example of indirect monitoring may be found in co-pending U.S. Pat. Application No. ~~10/087,877~~ 10/087,877, titled "INDIRECT MONITORING OF SEMICONDUCTOR LIGHT SOURCE WITHIN A PHOTONIC PACKAGE", contemporaneously filed and having at least partial common inventorship with the present application. The application is hereby fully incorporated by reference.

Please replace the paragraph beginning on page 14, line 3 with the following replacement paragraph:

FIGURE 3 illustrates monitoring of a semiconductor light source utilizing a beamsplitter within a photonic package, in accordance with an alternate embodiment of the present invention. Illustrated in FIG. 3, is a perspective view of a photonic package 300 incorporating the present invention. The photonic package 300 includes a substrate 302 upon which various components may be mounted. In the illustrated embodiment, mounted on the substrate 302 is a semiconductor light source 305, however, as described previously, it should be appreciated that commonly, numerous components may be mounted on the substrate 302. The semiconductor light source 305, in particular, has a front facet ~~307~~ 306. In the embodiment illustrated in FIG. 3, a single lens 307 is optically coupled to the front facet 306 of the semiconductor light source 305. Additionally, illustrated in FIG. 3, a first polarizing element 310 is optically coupled to the single lens 307, and a light isolator element 311 is optically coupled to the first polarizing element 310. Additionally, a second polarizing element 312 is optically coupled to the light isolator element 311, and a beam splitter cube (BSC) 313 is optically coupled to the second polarizing element 312, which in turn, may be coupled to an optical fiber (not shown).

Please replace the paragraph beginning on page 18, line 18 with the following replacement paragraph:

As alluded to earlier, in yet another embodiment, the first split output 331 from the BSC 313 may be indirectly monitored within the housing (not shown) of the photonic package 300. An example of indirect monitoring may be found in co-pending U.S. Pat. Application No. ~~10/087,877~~ 10/087,877, titled "INDIRECT MONITORING OF SEMICONDUCTOR LIGHT SOURCE WITHIN A PHOTONIC PACKAGE", contemporaneously filed and having at least partial common inventorship with the present application. The application is hereby fully incorporated by reference.